



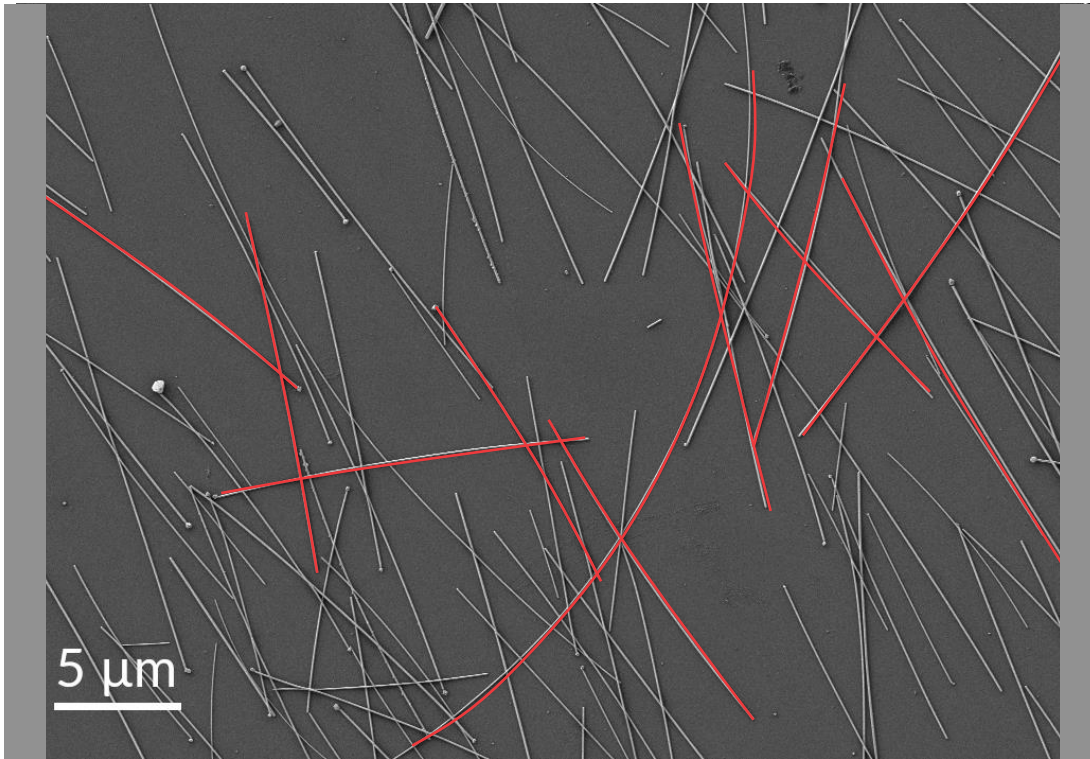
Mapping local failure of silver nanowire networks under electrical stresses

F. Balty^{1,2}, N. Lejeune², M. Rondiat¹, A. Baret¹, A. V. Silhanek², N. D. Nguyen¹

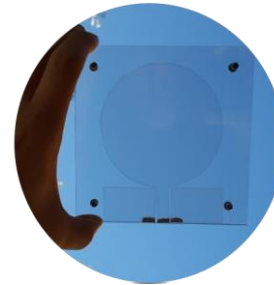
¹ SPIN – Solid state Physics of Interfaces and Nanostructures

² EPNM – Experimental Physics of Nanostructured Materials

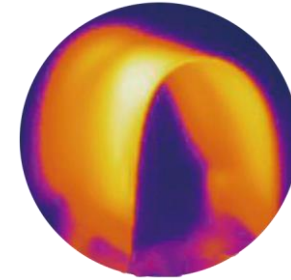
Metallic nanowire networks - Generalities



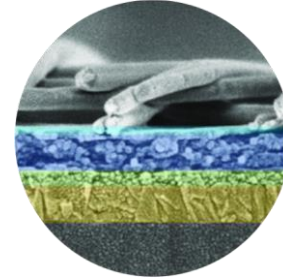
Conductive path between electrodes = « Percolation path » [1]



Transparent Antenna



Transparent Heater



Device integration



Photovoltaic

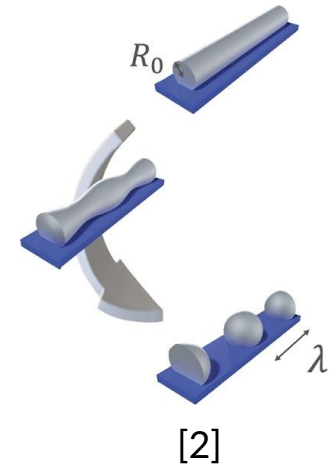
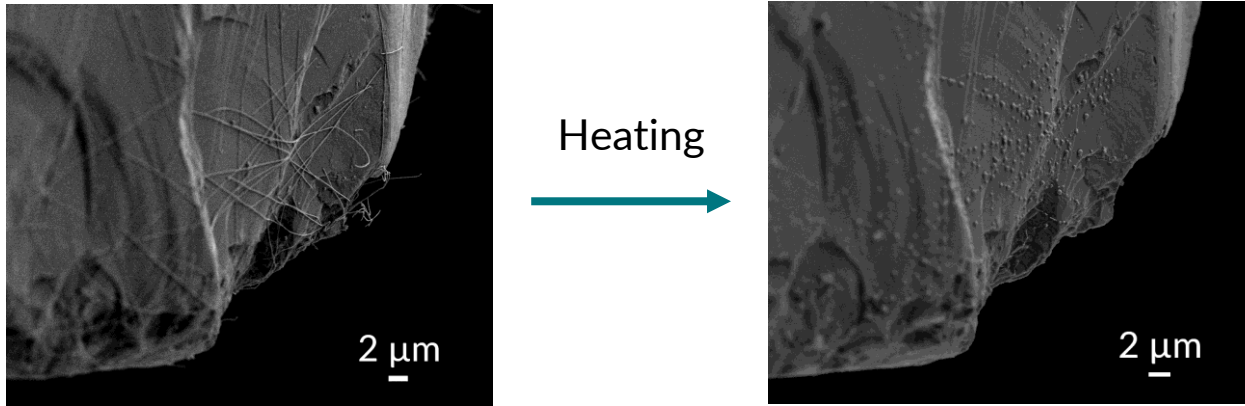


Touch screen



Flexible screen

Metallic nanowire networks - Instabilities

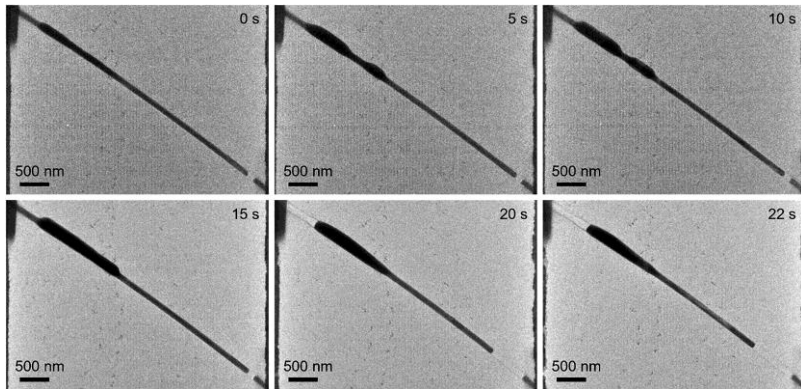
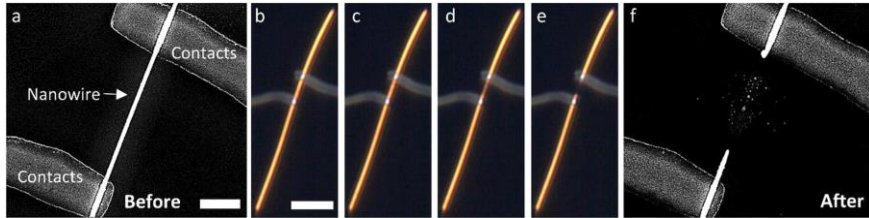


Prone to **instabilities** under a variety of stresses :

- Thermal
- Electrical
- Mechanical
- Chemical
- ...

Electrical instability – Literature

At the nanowire scale

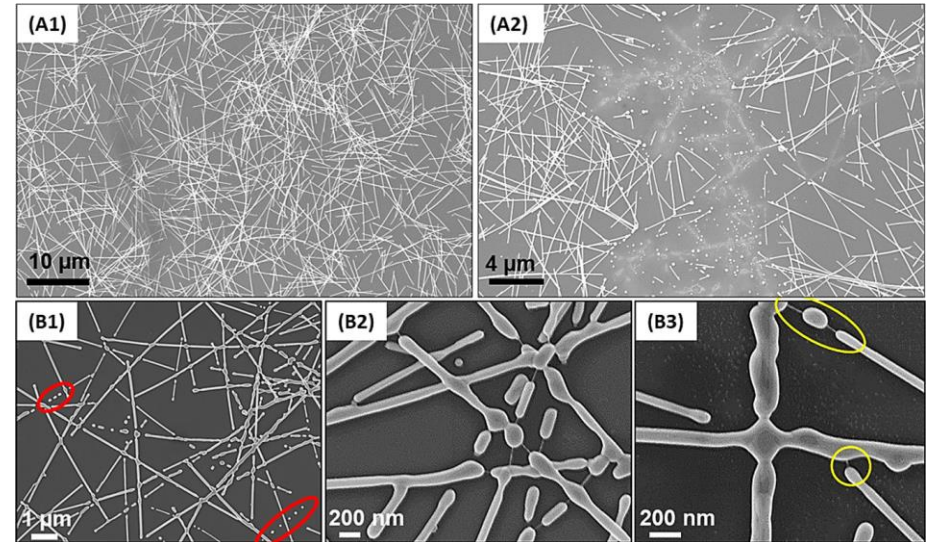


[3-5]

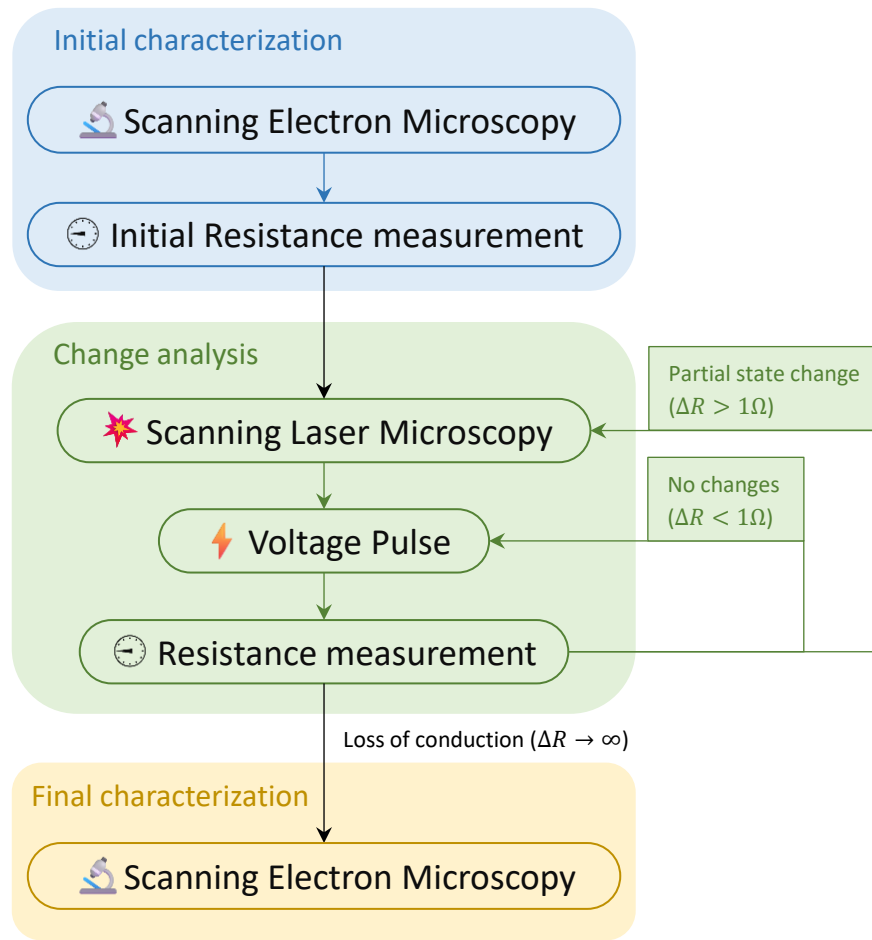
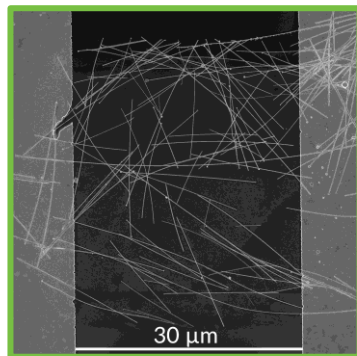
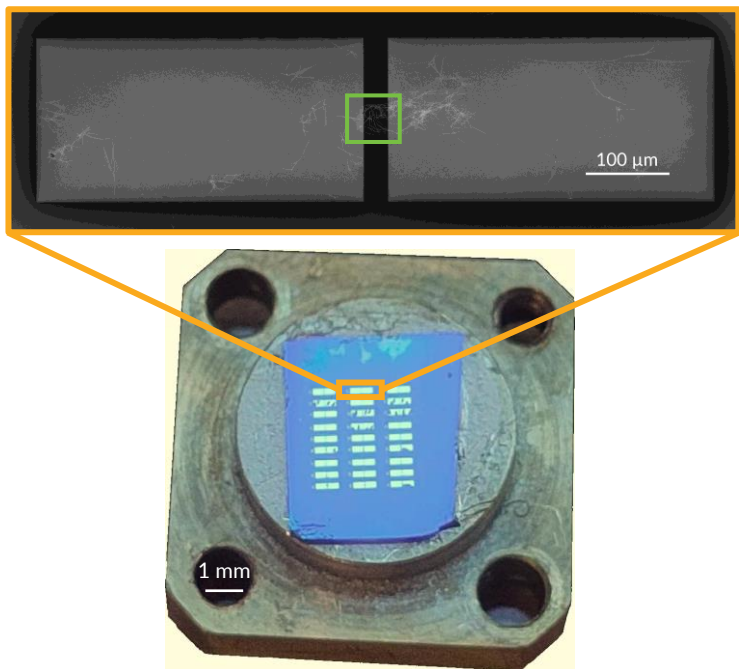
In between ?

[6-12]

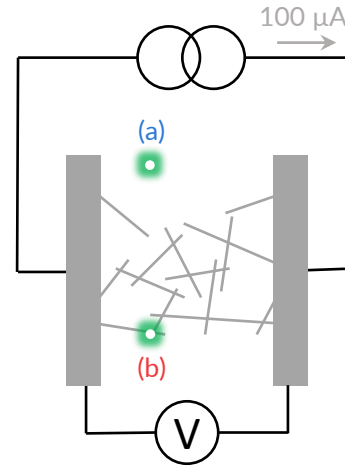
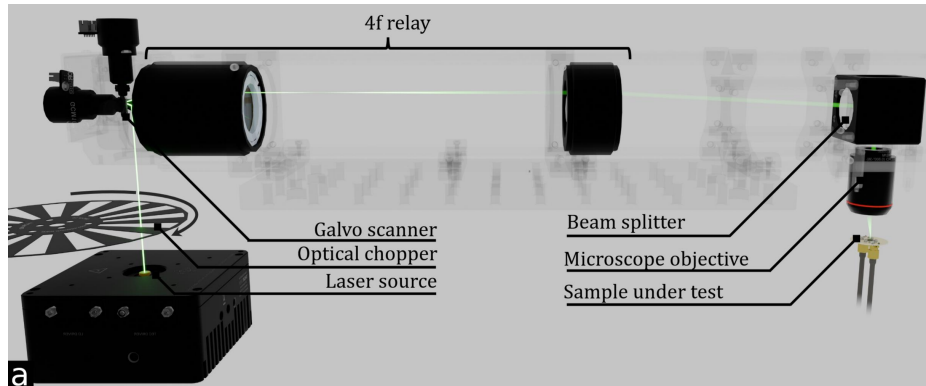
At the network scale



Micro-networks



Scanning Laser Microscopy – Percolation path observation



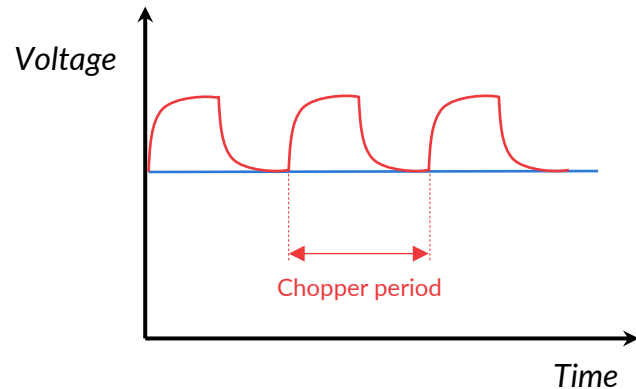
Case (a) : Laser on inactive zone

Case (b) : Laser on percolation path

- Resistivity $\rho \nearrow$ with $T \nearrow$

$$\Rightarrow R \nearrow \left(= \rho \frac{l}{S} \right)$$

$$\Rightarrow V \nearrow (= R i)$$

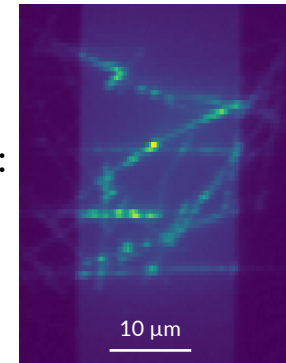


→ No perturbation

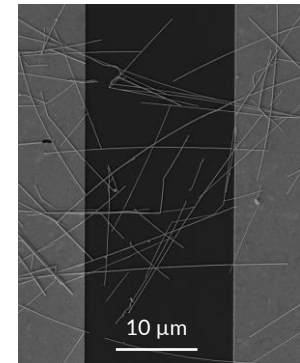
→ Perturbation

Scanning the whole area :

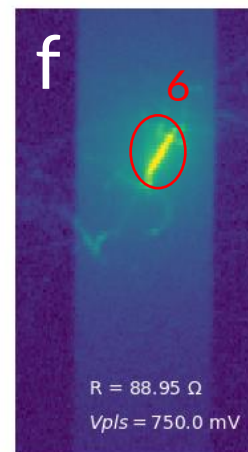
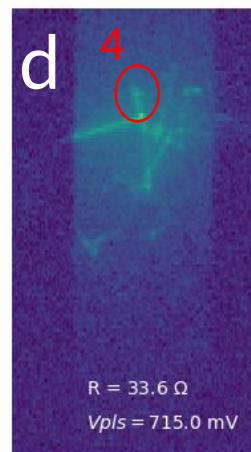
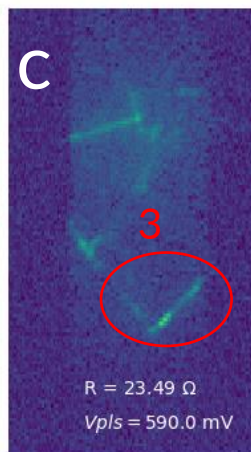
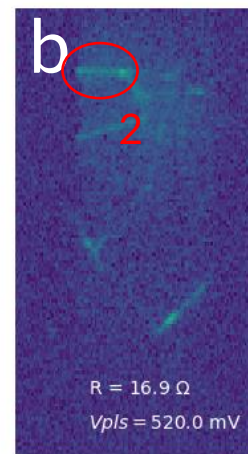
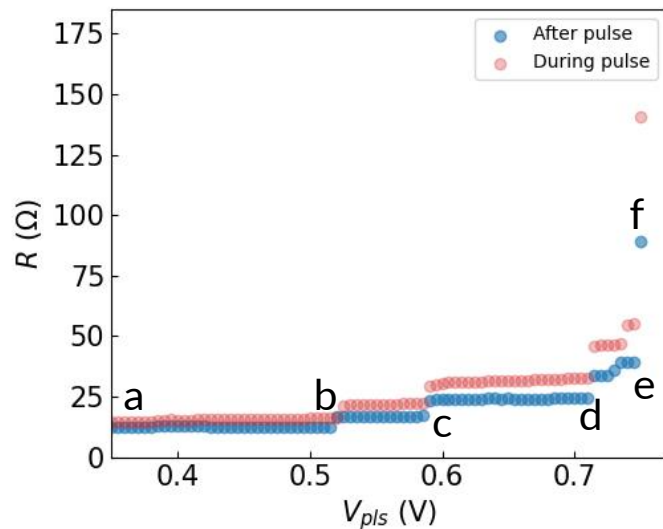
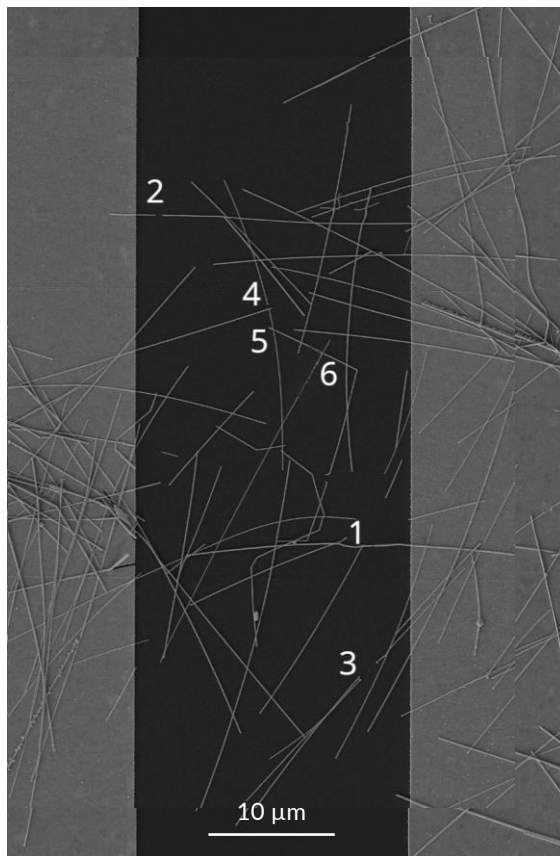
SLM



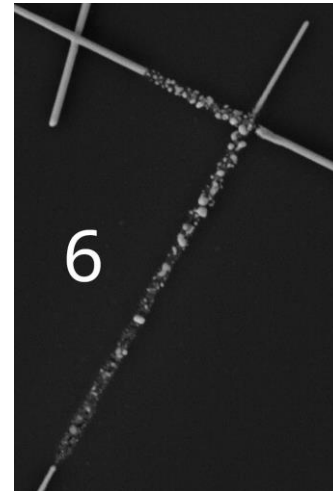
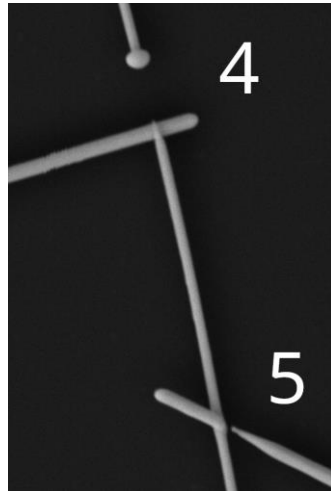
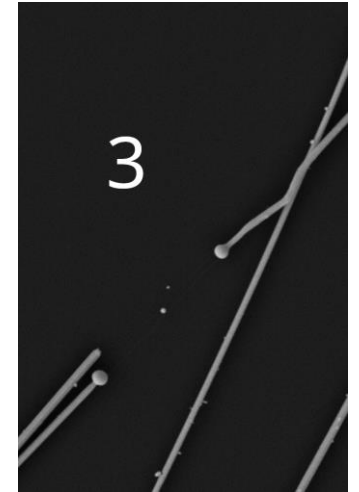
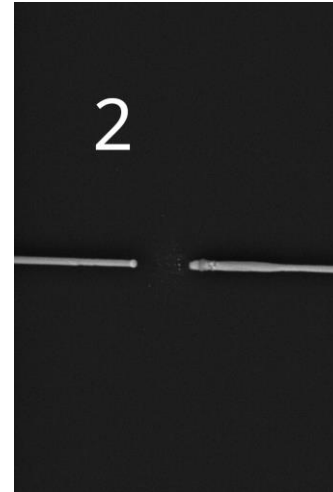
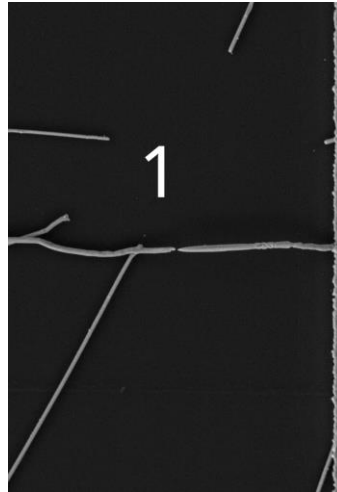
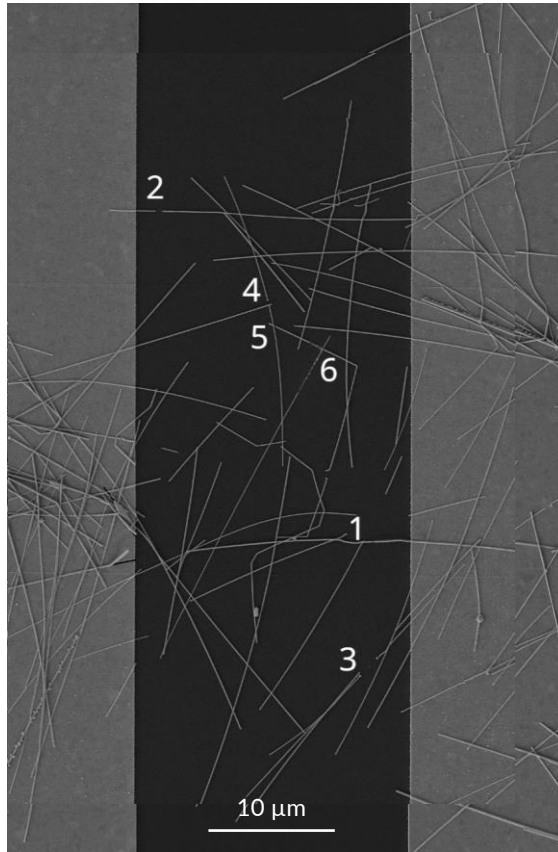
SEM



Results

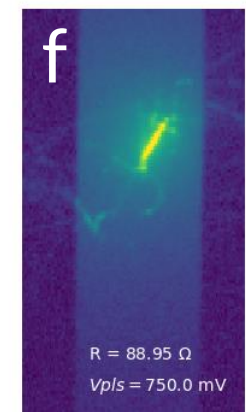
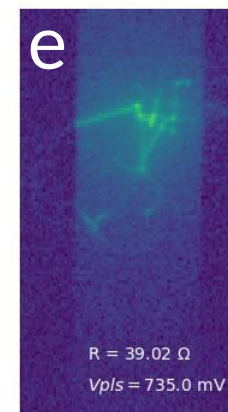
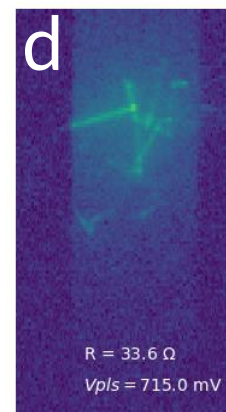
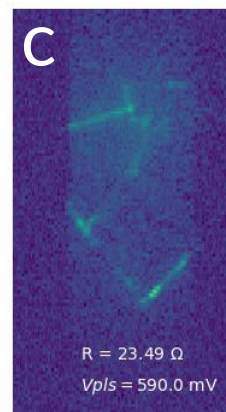
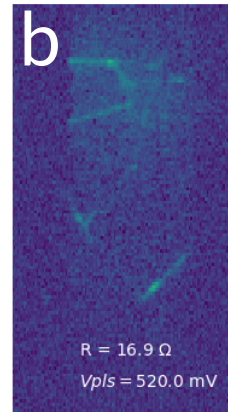
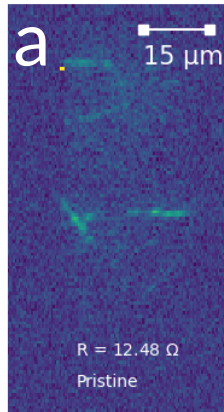


Results

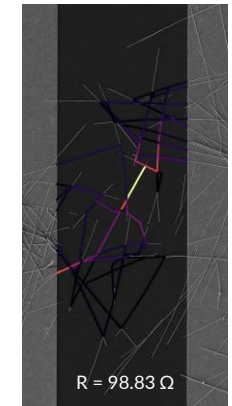
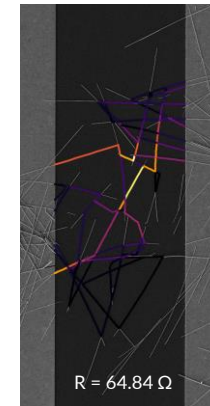
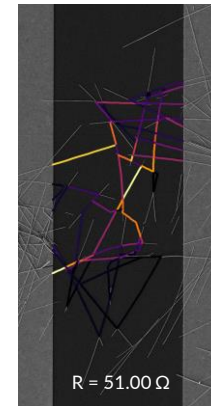
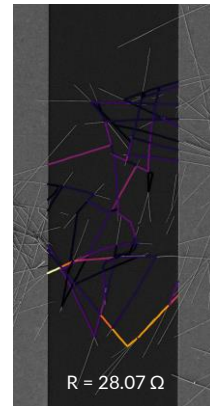
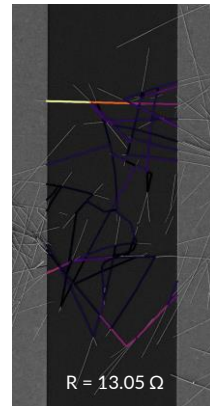
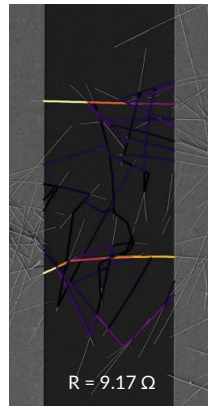


Comparison with digital twin simulation

Scanning
Laser
Microscopy



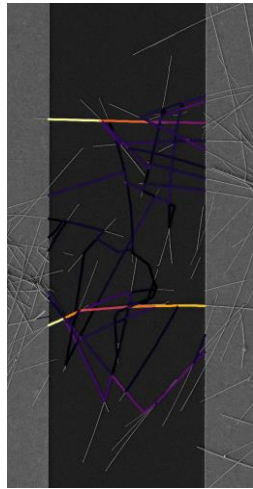
Colormap of the
simulated currents
(arbitrary units)



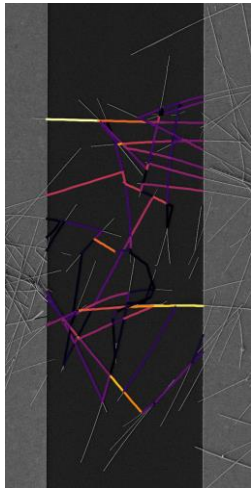
(Similar simulations : [1])

Simulation as a tool to interpret

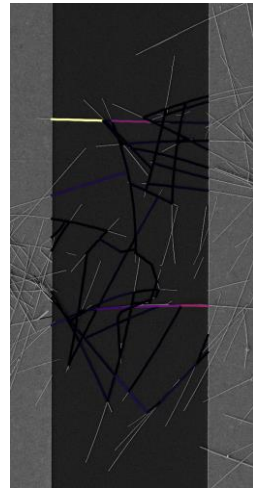
Numerical investigation on a variety of parameters :



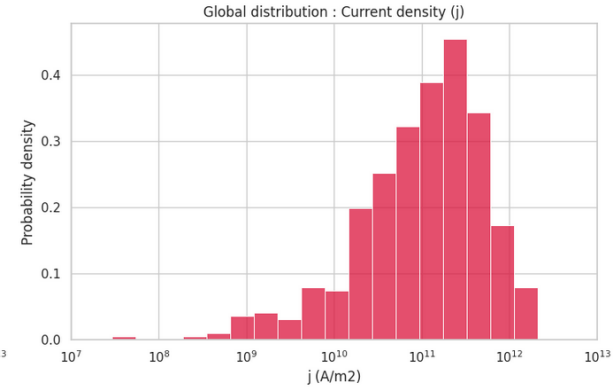
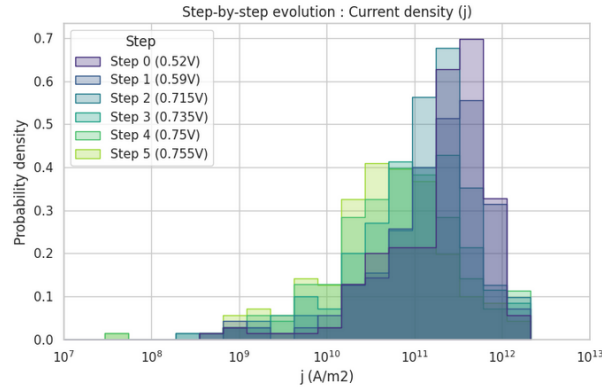
Current I



Current density j



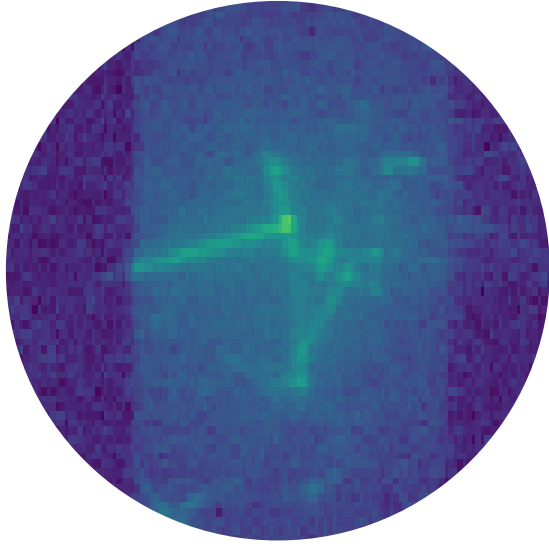
Dissipated power P



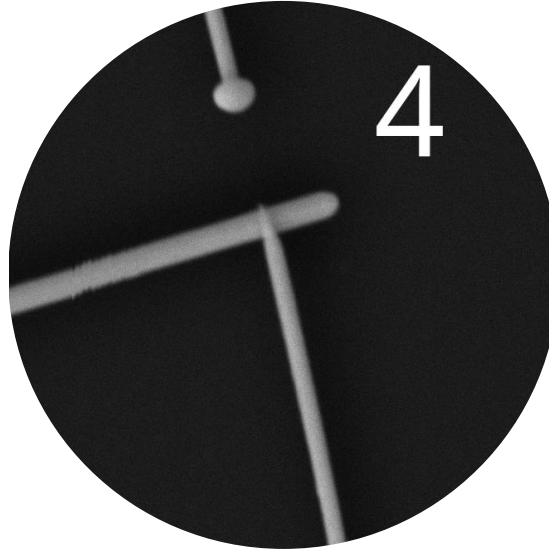
Preliminary results :

- Order of magnitude of stresses comparable to literature results
- Variety of failure morphology
- Stochastic failure – not always the NW with largest stress

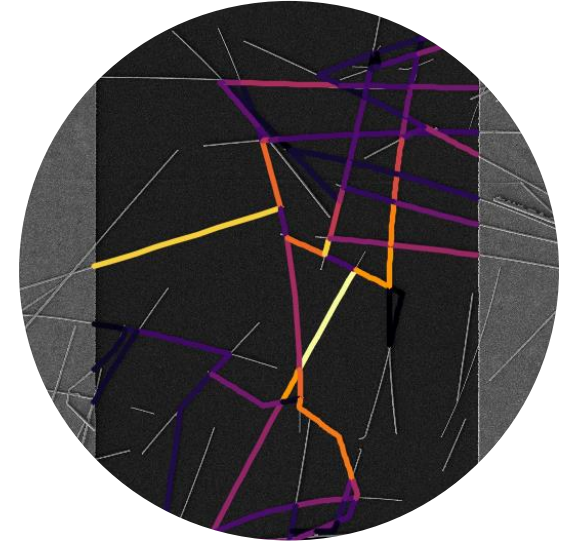
Take-home message



SLM is a spatially-resolved demonstration of the flow of current

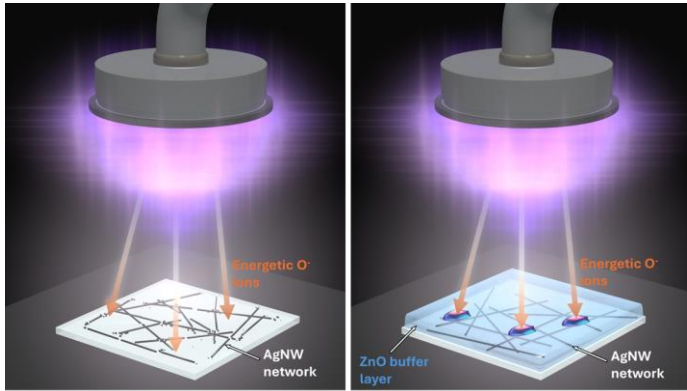


It allows to reconstruct the failure timeline of AgNW micro-network



Combined with simulations, it gives access to a large dataset

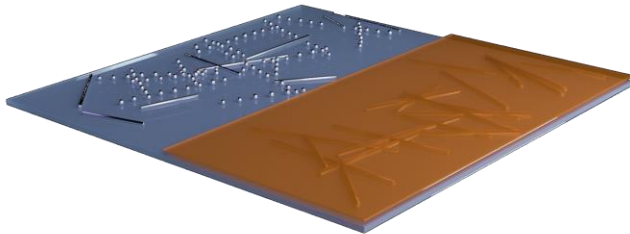
Other presentations from our group



*RF sputtering of metal oxides on nanostructured silver electrodes :
degradation mechanisms and stabilization strategies*

A. Baret, A. Khan, S. Akin, L. Teulé-Gay, D. Bellet, A. Rougier, N. D. Nguyen

Thursday 28/05, 15:00, Room ETOILE A



Enhancing the Stability of Silver Nanowire Networks with TiO_2 Thin Films

A. Baret, R. Zaghdoudi, F. Balty, Q. Binstok, D. Ndemekong, M. Georges, N. D. Nguyen

Thursday 28/05, 16:30-18:30, Poster session Room ETOILE

References

- [1] D. P. Langley, M. Lagrange, N. D. Nguyen, and D. Bellet, “Percolation in networks of 1-dimensional objects: comparison between Monte Carlo simulations and experimental observations,” *Nanoscale Horizons*, vol. 3, pp. 545–550, Aug. 2018.
- [2] F. Balty, A. Baret, A. Silhanek, and N. D. Nguyen, “Insight into the morphological instability of metallic nanowires under thermal stress,” *Journal of Colloid and Interface Science*, vol. 673, pp. 574–582, Nov. 2024.
- [3] T.-B. Song, Y. Chen, C.-H. Chung, Y. Yang, B. Bob, H.-S. Duan, G. Li, K.-N. Tu, and Y. Huang, “Nanoscale joule heating and electromigration enhanced ripening of silver nanowire contacts,” *ACS Nano*, vol. 8, no. 3, pp. 2804–2811, 2014. Number: 3.
- [4] M. Waliullah and R. A. Bernal, “Current density at failure of twinned silver nanowires,” *Nanotechnology*, vol. 33, p. 305706, July 2022.
- [5] K. Bejtka, M. Allione, C. Ricciardi, C. F. Pirri, and G. Milano, “Real-Time TEM Observation of the Microstructural Evolution in Silver Nanowires under Heating and Electrical Biasing,” *ACS Applied Electronic Materials*, vol. 8, pp. 1156–1165, Feb. 2026.
- [6] H. H. Khaligh and I. A. Goldthorpe, “Failure of silver nanowire transparent electrodes under current flow,” *Nanoscale Research Letters*, vol. 8, p. 235, May 2013.
- [7] C. Mayousse, C. Celle, A. Fraczkiewicz, and J.-P. Simonato, “Stability of silver nanowire based electrodes under environmental and electrical stresses,” *Nanoscale*, vol. 7, pp. 2107–2115, Jan. 2015. 145 citations (Crossref) [2023-10-20].



References

- [8] M. Lagrange, T. Sannicolo, D. Muñoz-Rojas, B. G. Lohan, A. Khan, M. Anikin, C. Jiménez, F. Bruckert, Y. Bréchet, and D. Bellet, “Understanding the mechanisms leading to failure in metallic nanowire-based transparent heaters, and solution for stability enhancement,” *Nanotechnology*, vol. 28, p. 055709, Dec. 2016.
- [9] T. Sannicolo, N. Charvin, L. Flandin, S. Kraus, D. T. Papanastasiou, C. Celle, J.-P. Simonato, D. Muñoz-Rojas, C. Jiménez, and D. Bellet, “Electrical Mapping of Silver Nanowire Networks: A Versatile Tool for Imaging Network Homogeneity and Degradation Dynamics during Failure,” *ACS Nano*, vol. 12, pp. 4648–4659, May 2018.
- [10] K. Wang, Y. Jin, X. Wang, B. Qian, J. Wang, and F. Xiao, “Investigation into the failure mechanism of silver nanowire network film under electrical stress,” in *2020 IEEE 70th Electronic Components and Technology Conference (ECTC)*, pp. 1218–1224, June 2020.
- [11] K. Wang, Y. Jin, and F. Xiao, “Long-term electrically stable silver nanowire composite transparent electrode under high current density,” *Journal of Materials Science: Materials in Electronics*, vol. 32, pp. 20919–20935, Aug. 2021.
- [12] N. Charvin, J. Resende, D. T. Papanastasiou, D. Muñoz-Rojas, C. Jiménez, A. Nourdine, D. Bellet, and L. Flandin, “Dynamic degradation of metallic nanowire networks under electrical stress: a comparison between experiments and simulations,” *Nanoscale Advances*, vol. 3, no. 3, pp. 675–681, 2021.

